

SEMICONDUCTOR PACKAGE WITH CHAMFERED CORNERS AND METHOD
OF MANUFACTURING THE SAME

ABSTRACT OF THE INVENTION

[0048] A semiconductor package comprising a die paddle defining multiple corners and opposed first and second surfaces. At least one set of leads extends at least partially about the die paddle in spaced relation thereto. Each of the leads has opposed first and second surfaces. Attached to and extending from one of the corners of the die paddle is at least one tie bar which itself has opposed first and second surfaces and at least one aperture disposed therein and extending between the first and second surfaces thereof. Attached to the first surface of the die paddle is a semiconductor die which is electrically connected to at least one of the leads. A package body at least partially covers the die paddle, the leads, the tie bar and the semiconductor die such that the second surfaces of the leads are exposed in and substantially flush with a common exterior surface of the package body, and a portion of the package body extends through the aperture of the tie bar.